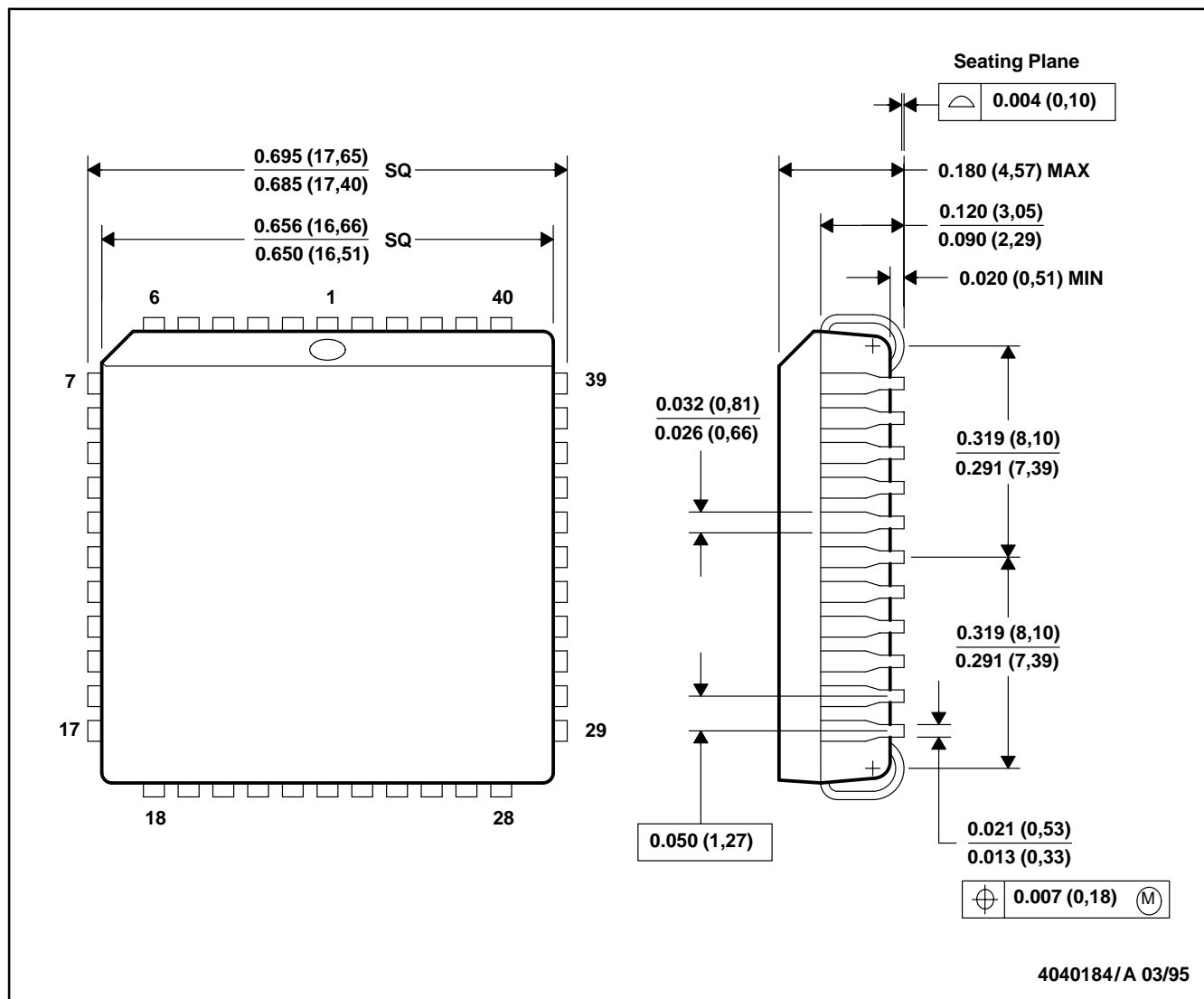


FNH (S-PQCC-J44)

PLASTIC J-LEADED CHIP CARRIER



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - Falls within JEDEC MS-018
 - Thermally enhanced molded plastic package with leads 19 through 27 connected to the die pad.

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